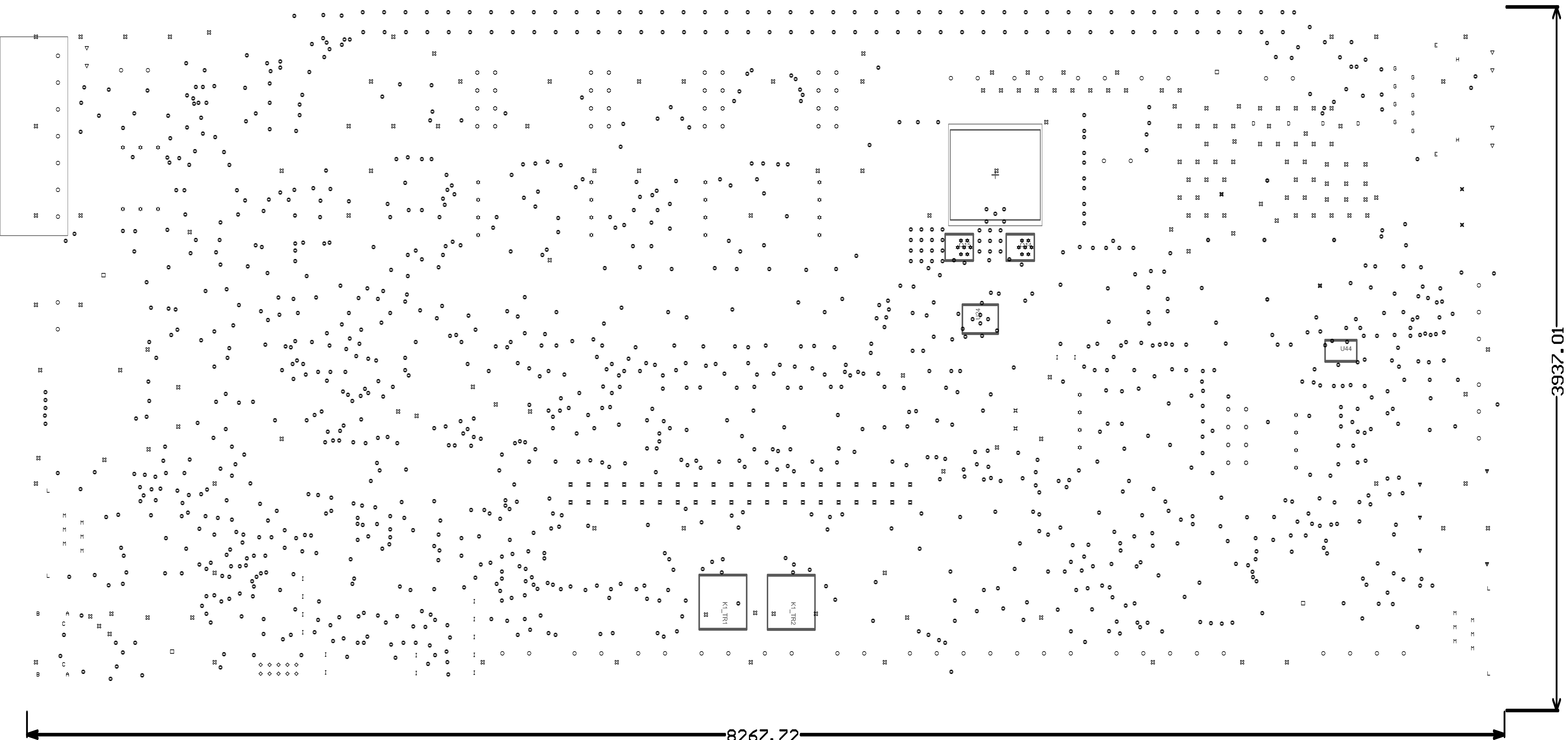


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric 3	PP-006	7.87mil	4.5	
2	GND	CF-004	1.38mil		
	Dielectric1	FR-4	39.37mil	4.8	
3	PWR	CF-004	1.38mil		
	Dielectric 4	PP-006	7.87mil	4.5	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				
Total board thickness:			61.47mil		

- NOTES: UNLESS OTHERWISE SPECIFIED, ALL DIMENSIONS ARE IN INCHES.
- MATERIAL: EPOXY GLASS FR-4 UL94V-0 HIGHEST IN STOCK AVAILABLE Tg. FABRICATE PCB IN ACCORDANCE WITH IPC-6012, CLASS2; PER IPC-6011.
  - HOLE LOCATION TOLERANCE +/- .003 DIAMETER OF TRUE POSITION. ARTWORK REGISTRATION FRONT TO BACK +/- .003
  - ALL PLATED THROUGH HOLES TO HAVE A MINIMUM PLATING OF .0007 COPPER. ANNULAR RING TO BE .001 MIN. VIA HOLES MAY HAVE A .001 ANNULAR RING. TEARDROPS MAY BE ADDED TO AVOID DRILL BREAKOUT.
  - LPI (LIQUID PHOTO IMAGABLE) SOLDERMASK PER IPC-SM-840, TYPE B, CLASS H BOTH SIDES, COLOR: BLACK WITH MAXIMUM MISREGISTRATION TO BE .003 OVER BARE COPPER. ALL EXPOSED COPPER AREAS, BOTH SIDES TO BE PLATED 2-6 MICROINCHES ELECTROLESS GOLD OVER 120 MICROINCHES ELECTROLESS NICKEL. MANUFACTURER MAY MODIFY SOLDERMASK TO REMOVE ANY SLIVERS THAT ARE .004 OR LESS BETWEEN FINE PITCHED LANDS.
  - SILKSCREEN BOTH SIDES USING WHITE EPOXY INK. MANUFACTURER MUST MODIFY SLIKSCREEN IMAGE TO REMOVE ANY WHITE EPOXY INK FROM EXPOSED METAL.
  - IF REQUIRED, MAXIMUM RADIUS ON ALL INSIDE CORNERS TO BE .025
  - MANUFACTURER TO MARK BOARD WITH COPPER OR WHITE EPOXY INK, IN AN OPEN AREA ON BOTTOM SIDE, DESIGNATED WITH A DATE CODE INDICATING YEAR AND WEEK OF FABRICATION, 4 DIGIT FORMAT
  - FINISHED BOARD TO COMPLY WITH PHYSICAL AND ENVIRONMENTAL REQUIREMENTS OF IPC-A-600. BOW AND TWIST PER 10-3, CLASS 2, MULTI AND UL796
  - REFERENCE ONLY: APPROXIMATE MINIMUM LINE IS .004 AND SPACE IS .005
  - UNLESS OTHERWISE SPECIFIED, BOARD SHALL BE .062 NOMINAL THICKNESS

DRILL DRAWING



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Pad Shape
⊙	1283	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	Rounded
⊗	168	19.69mil (0.500mm)	PTH	Round	Top Layer - Bottom Layer	Rounded
○	57	55.12mil (1.400mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)
⊕	40	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)
⊞	40	43.31mil (1.100mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)
☆	30	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)
I	15	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)
✱	14	9.84mil (0.250mm)	PTH	Round	Top Layer - Bottom Layer	Rounded
M	12	35.43mil (0.900mm)	PTH	Slot	Top Layer - Bottom Layer	Rounded
◇	10	27.56mil (0.700mm)	PTH	Round	Top Layer - Bottom Layer	Rounded
G	8	35.04mil (0.890mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)
▽	6	40.16mil (1.020mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)
▼	5	78.74mil (2.000mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)
⊗	5	99.87mil (2.537mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)
D	4	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)
L	4	98.43mil (2.500mm)	NPTH	Round	Top Layer - Bottom Layer	Rounded
□	4	157.48mil (4.000mm)	NPTH	Round	Top Layer - Bottom Layer	Rounded
B	2	25.59mil (0.650mm)	PTH	Slot	Top Layer - Bottom Layer	Rounded
A	2	25.59mil (0.650mm)	PTH	Slot	Top Layer - Bottom Layer	Rounded
C	2	27.56mil (0.700mm)	NPTH	Round	Top Layer - Bottom Layer	Rounded
⊗	2	51.18mil (1.300mm)	PTH	Round	Top Layer - Bottom Layer	(Mixed)
E	2	64.17mil (1.630mm)	PTH	Round	Top Layer - Bottom Layer	Rounded
⊗	2	74.80mil (1.900mm)	PTH	Round	Top Layer - Bottom Layer	Rounded
⊗	2	90.87mil (2.308mm)	NPTH	Round	Top Layer - Bottom Layer	Rounded
H	2	127.95mil (3.250mm)	NPTH	Round	Top Layer - Bottom Layer	Rounded
	1721 Total					

Slot definitions : Routed Path Length = Calculated from tool start centre position to tool end centre position.  
Hole Length = Routed Path Length + Tool Size = Slot length as defined in the PCB layout

